

TOREX SEMICONDUCTOR LTD.
Quality Assurance Dept.

Composition Table

Product(Pb-free): XC6109xxxxNR-G

Typical Mass: 7 mg

Part name	Weight(mg)	Material name	Ratio(ppm)	CAS number
Silicon chip	0.197	Silicon	28100	7440-21-3
		- Arsenic	2	7440-38-2
Leadframe	2.790	Copper	398500	7440-50-8
		Tin	9400	7440-31-5
		Zinc	100	7440-66-6
		Chromium	400	7440-47-3
		Silver	10100	7440-22-4
		Die attach	0.013	Silver
	0.001	Epoxy	200	—
Bonding wire	0.059	Gold	8400	7440-57-5
Resin	3.168	Silica	452500	60676-86-0
		Epoxy Resin	36000	—
		Phenol Resin	25700	—
Plating	0.200	Tin	28600	7440-31-5

* The component composition is based on the information provided by raw material vender.

* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

* Any indication "-" in CAS number means "confidential."